


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/19/11567	
1.3 Title of PCN	Mold compound replacement for ISOTOP automotive	
1.4 Product Category	YPS200170TV16H%7	
1.5 Issue date	2019-05-20	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Richard RENARD
2.1.2 Marketing Manager	Philippe LEGER
2.1.3 Quality Manager	Jean-Paul REBRASSE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Mold compound	ST assy site in Morocco

4. Description of change

	Old	New
4.1 Description	Samsung SDI product termination of the following references of molding compound for through hole packages	Replacement of current mold compounds with alternative material. ST is already proceeding with new resins evaluation and qualification, to guarantee adequate products continuity
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no	

5. Reason / motivation for change

5.1 Motivation	Product discontinuance from current supplier.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	internal codification and QA number
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7. Timing / schedule

7.1 Date of qualification results	2019-08-26
7.2 Intended start of delivery	2019-12-02
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)		
11567 Public product.pdf 11567 PCN-ISOTOP automotive.pdf		
10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STPS200170TV1Y	

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(1) ADG: Automotive and Discrete Group

<p align="center">PCN</p> <p align="center">Product/Process Change Notification</p>			
<p align="center">Mold compound replacement for ISOTOP automotive</p>			
Notification number:	ADG-DIS/19/11567	Issue Date	15/05/2019
Issued by	Aline Augis		
Product series affected by the change		Automotive rectifiers in ISOTOP package. YPS200170TV16H%Z	
Type of change		Back end realization	
<p>Description of the change</p> <p>Following 11478 Early Notification sent in Week 15-2019, the change is the mold compound replacement for ISOTOP package.</p>			
<p>Reason for change</p> <p>Product discontinuance from current supplier.</p>			
Former versus changed product:		<p>The changed products do not present modified electrical, dimensional or thermal parameters, leaving unchanged the current information published in the product datasheet</p> <p>The footprint recommended by ST remains the same.</p> <p>There is no change in the packing modes and the standard delivery quantities either.</p> <p>The products remain in full compliance with the ST ECOPACK®2 grade ("halogen-free").</p>	
<p>Disposition of former products</p> <p>Delivery of current product will be done until stock depletion.</p>			
<p>Marking and traceability</p> <p>No change of marking. Traceability through new finished good codes (printed on labels).</p>			
Qualification forecasted date		Week 35-2019	
<p>Forecasted sample availability</p> <p>Samples will be available on demand with a typical lead time of 5 weeks after order entry.</p>			

(1) ADG: Automotive and Discrete Group

Change implementation schedule

Sales types	Estimated production start	Estimated first shipments
All Commercial Products	Week 36-2019	Week 49-2019

Comments: With early PCN acceptance, possible shipment starting on W37 on selected part numbers.

Customer's feedback

Please contact your local ST sales representative or quality contact for requests concerning this change notification.

Absence of acknowledgement of this PCN within 30 days of receipt will constitute acceptance of the change

Absence of additional response within 180 days of receipt of this PCN will constitute acceptance of the change

Qualification program:

Qualification will be performed through a global plan with the following Product Test Vehicles.

PTV (FG) - ISOTOP
STTH6112TV1H/Z (Non-auto)
YPS200170TV16H%7 (Automotive)
STTH16003TV1-H/Z (Non-auto)

Reliability tests will be conducted following below table.

Stress	Abrv	Reference
High Temperature Reverse Bias	HTRB	MIL-STD-750-1 M1038 Method A (for diodes, rectifiers)
AC blocking voltage	ACBV	MIL-STD-750-1 M1040 Test condition A (for SCR)
High Humidity High Temperature Reverse Bias	H3TRB	JESD22A-101
Unbiased Highly Accelerated Stress Test	UHAST	JESD22A-118 or A101
Temperature Cycling	TC	JESD22A-104
Intermittent Operational Life / Thermal Fatigue	IOL	MIL-STD-750 Method 1037
Destructive Physical Analysis	DPA	AEC-Q101-004 Section 4



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : Mold compound replacement for ISOTOP automotive

PCN Reference : ADG/19/11567

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STPS200170TV1Y		
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